



Material Content Data Sheet



Sales Product Name				BTS50055-1TMB		Issued		27. September 2017	
MA#				MA000907884					
Package				PG-TO220-7-11		Weight*		2124.25 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	15.514	0.73	0.73	7303	7303	
leadframe	non noble metal	iron	7439-89-6	0.908	0.04		427		
	inorganic material	phosphorus	7723-14-0	0.272	0.01		128		
	non noble metal	copper	7440-50-8	906.793	42.69	42.74	426877	427432	
wire	non noble metal	aluminium	7429-90-5	5.318	0.25	0.25	2503	2503	
encapsulation	organic material	carbon black	1333-86-4	8.705	0.41		4098		
	plastics	epoxy resin	-	95.752	4.51		45076		
	inorganic material	silicondioxide	60676-86-0	475.857	22.40	27.32	224012	273186	
leadfinish	non noble metal	tin	7440-31-5	23.005	1.08	1.08	10830	10830	
plating	non noble metal	nickel	7440-02-0	0.216	0.01	0.01	102	103	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
glue	plastics	Polyimide	26023-21-2	0.217	0.01	0.01	102	102	
solder	noble metal	silver	7440-22-4	0.203	0.01		95		
	non noble metal	tin	7440-31-5	0.162	0.01		76		
	non noble metal	lead	7439-92-1	7.743	0.36	0.38	3645	3816	
heatspreader	non noble metal	iron	7439-89-6	0.584	0.03		275		
	inorganic material	phosphorus	7723-14-0	0.175	0.01		82		
	non noble metal	copper	7440-50-8	582.824	27.44	27.48	274368	274725	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com